

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** **0736560000**  
**Status:** **Active**  
**Overview:** [hdm](#)  
**Description:** 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm (30µ")

**Documents:**

[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

CSA LR19980  
 UL E29179

**General**

Product Family Backplane Connectors  
 Series [73656](#)  
 Application Backplane  
 Comments Backplane Power Module  
 Component Type Power Header  
 Overview [hdm](#)  
 Product Name HDM®  
 Style N/A

**Physical**

Circuits (Loaded) 3  
 Circuits (maximum) 3  
 Color - Resin Black  
 Durability (mating cycles max) 250  
 First Mate / Last Break No  
 Flammability 94V-0  
 Guide to Mating Part No  
 Keying to Mating Part None  
 Material - Metal Beryllium Copper  
 Material - Plating Mating Gold  
 Material - Plating Termination Gold  
 Material - Resin High Temperature Thermoplastic  
 Number of Columns 1  
 Number of Pairs Open Pin Field  
 Number of Rows 3  
 Orientation Vertical  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.098 In  
 PCB Thickness Recommended (mm) 2.50 mm  
 Packaging Type Tube  
 Pitch - Mating Interface (in) 0.138 In  
 Pitch - Mating Interface (mm) 3.50 mm  
 Plating min: Mating (µin) 30  
 Plating min: Mating (µm) 0.75  
 Plating min: Termination (µin) 2  
 Plating min: Termination (µm) 0.05  
 Polarized to PCB No  
 Surface Mount Compatible (SMC) Yes  
 Temperature Range - Operating -55°C to +105°C  
 Termination Interface: Style Through Hole - Compliant Pin

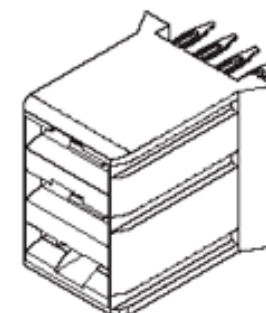


image - Reference only

Series

**EU RoHS**

**ELV and RoHS Compliant**

**REACH SVHC**

**Contains SVHC: No**

**Halogen-Free**

**Status**

**Halogen-Free**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73656Series](#)

**Mates With**

[73651](#) HDM® Board-to-Board Daughterboard Power Module

**Application Tooling | FAQ**

*Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.*

**Global**

Description	Product #
Flat Rock Tooling for Pneumatic Press	<a href="#">0622013700</a>
HDM® Backplane Power Module Loading Heads	<a href="#">0622005711</a>

**Electrical**

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Voltage - Maximum	500V AC

**Material Info****Reference - Drawing Numbers**

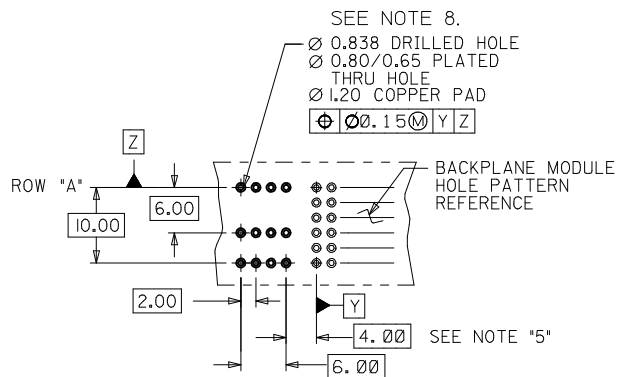
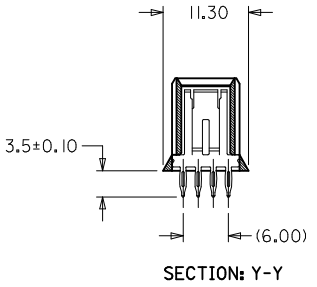
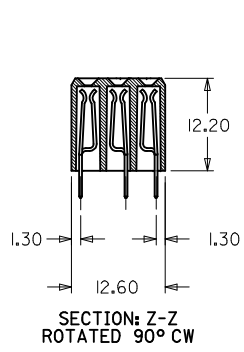
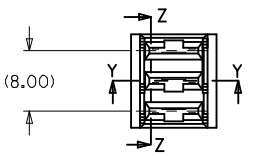
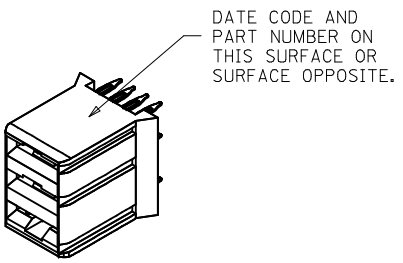
Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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ASSEMBLY NUMBER	FINISH
73656-0000	SEE NOTE 2.
73656-0001	SEE NOTE 3.



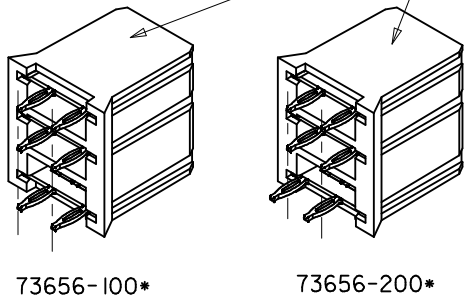
PCB LAYOUT: COMPONENT SIDE  
RECOMMENDED PCB THICKNESS: 2.50 MIN

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK  
TERMINAL - COPPER ALLOY
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: NICKEL (Ni) AND GOLD FLASH OVERALL
3. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: TIN/LEAD (Sn/Pb) OVER NICKEL (Ni) IN COMPLIANT AREA: NICKEL (Ni) OVERALL ON REMAINING WITH SELECTIVE GOLD (Au) FLASH.
4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00 mm.
5. DIMENSIONS ARE IN MILLIMETERS.
6. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
7. PACKAGE ASSEMBLIES PER PK-70873-0819.
8. HOLE SIZE SPECIFICATION IS FOR TIN/LEAD PLATED HOLES ONLY. FOR OTHER PLATING TYPES SEE MOLEX APPLICATION AS-73670-9996.
9. THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS B.

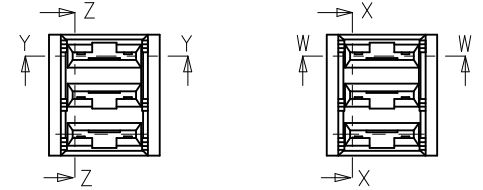
<b>ADD NOTES 8 &amp; 9</b> EC NO: UCP2009-1813 DRWNS:DANNELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± .005</td> <td>± .0004</td> </tr> <tr> <td>3 PLACES</td> <td>± .008</td> <td>± .0006</td> </tr> <tr> <td>2 PLACES</td> <td>± .015</td> <td>± .0012</td> </tr> <tr> <td>1 PLACE</td> <td>± .030</td> <td>± .0024</td> </tr> </table>		mm	INCH	4 PLACES	± .005	± .0004	3 PLACES	± .008	± .0006	2 PLACES	± .015	± .0012	1 PLACE	± .030	± .0024	DIMENSION STYLE <b>MM ONLY</b> DRAWN BY DATE ELO 1998/05/21 CHECKED BY DATE SMR 1998/05/21 APPROVED BY DATE CAB 1998/05/21	SCALE <b>1:1</b> DESIGN UNITS <b>METRIC</b> THIRD ANGLE PROJECTION	TITLE <b>SALES ASSY, HDM BACKPLANE POWER MODULE (PRESSFIT)</b> <b>MOLEX INCORPORATED</b> MATERIAL NO. <b>SEE TABLE</b> DOCUMENT NO. <b>SDA-73656-*00*</b>	SHEET NO. <b>1 OF 4</b>
		mm	INCH																		
	4 PLACES	± .005	± .0004																		
	3 PLACES	± .008	± .0006																		
2 PLACES	± .015	± .0012																			
1 PLACE	± .030	± .0024																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																				

DATE CODE AND  
PART NUMBER ON  
THIS SURFACE OR  
SURFACE OPPOSITE.

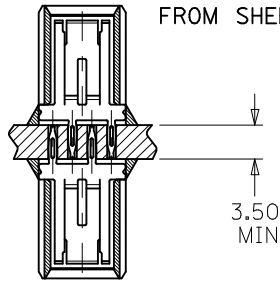


### MIDPLANE OPTION

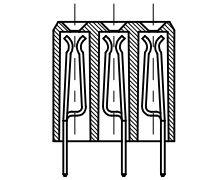
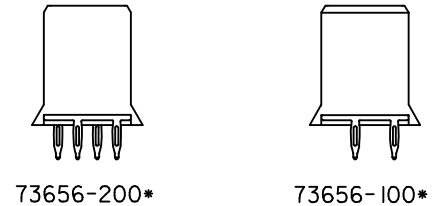
ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	



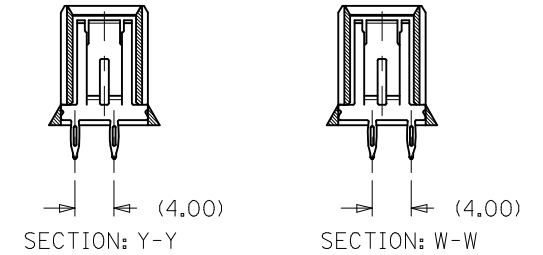
USE BACKPLANE MODULE  
HOLE REFERENCE PATTERN  
FROM SHEET 1



BACK-TO-BACK  
MOUNTING APPLICATION

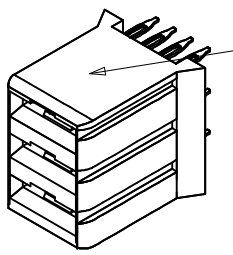


SECTION X-X  
SECTION Z-Z  
ROTATED 90° CW

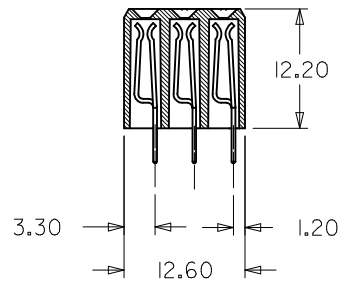
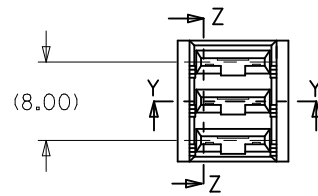


SEE SHEET 1 EC NO: UCP2009-1813 DRWN: SDANNELLEY 2009/07/17 CHKD: BSMART 2009/07/24 APPR: SMILLER 2009/07/24	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	m/m INCH ± --- ± --- ± --- ± --- ± --- ± --- ± --- ± ---	DRAWN BY ELO	DATE 1998/05/21	TITLE SALES ASSY, HDM BACKPLANE POWER MODULE (PRESSFIT)					
		ANGULAR ±1/2°		CHECKED BY SMR	DATE 1998/05/21	MOLEX INCORPORATED					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY CAB	DATE 1998/05/21	MATERIAL NO. SEE TABLE	DOCUMENT NO. SDA-73656-*00*	SHEET NO. 2 OF 4			

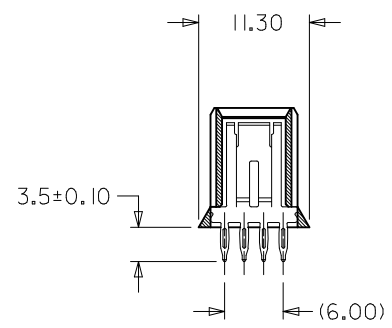
10	9	8	7	6	5	4	3	2	
ASSEMBLY NUMBER		FINISH (SHT I)							
73656-5000		SEE NOTE 2.							
73656-5001		SEE NOTE 3.							



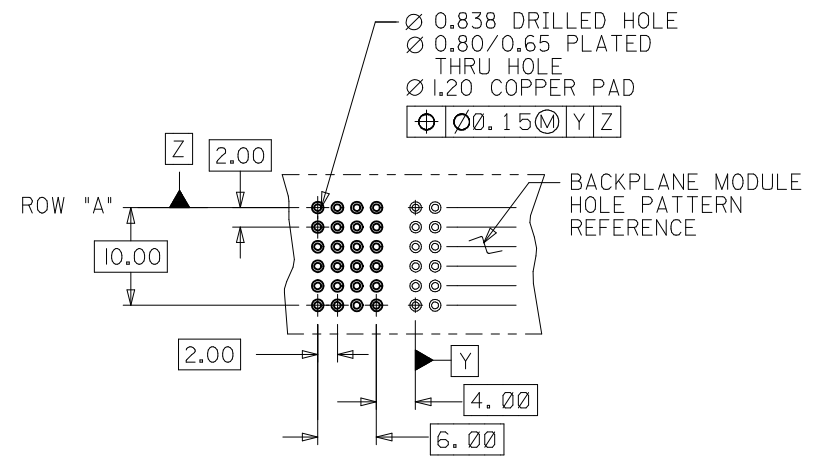
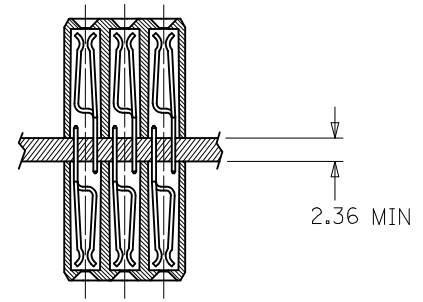
DATE CODE AND PART NUMBER ON THIS SURFACE OR SURFACE OPPOSITE.



SECTION: Z-Z  
ROTATED 90° CW



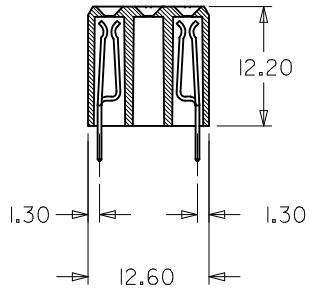
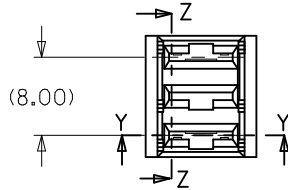
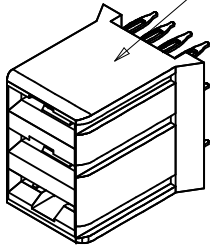
SECTION: Y-Y



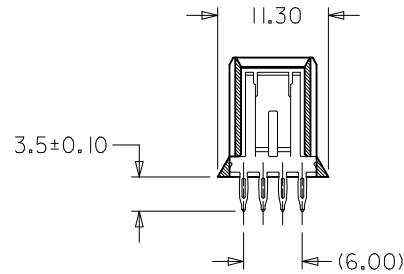
SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANNELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ±1/2°	DIMENSION STYLE MM ONLY DRAWN BY DATE ELO 1998/05/21 CHECKED BY DATE SMR 1998/05/21 APPROVED BY DATE CAB 1998/05/21	SCALE 1:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SDA-73656-*00*	SHEET NO. 3 OF 4	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		MOLEX INCORPORATED				
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ASSEMBLY NUMBER	FINISH
73656-0180	SEE NOTE 2.
73656-0181	SEE NOTE 3.

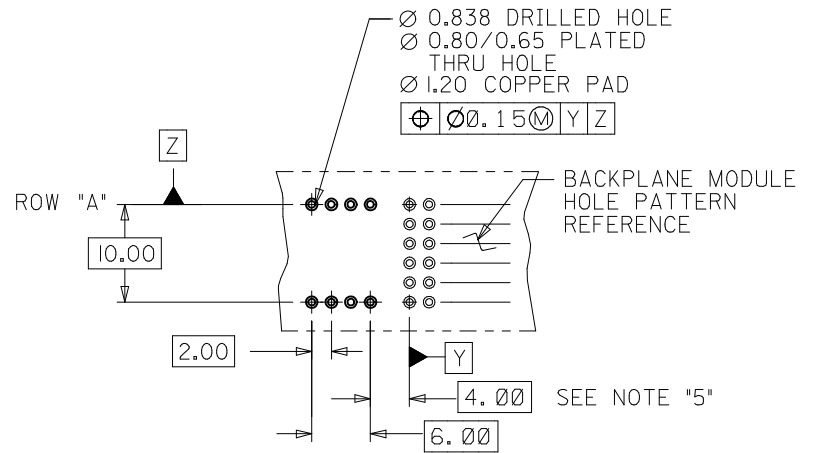
DATE CODE AND PART NUMBER ON THIS SURFACE OR SURFACE OPPOSITE.



SECTION: Z-Z  
ROTATED 90° CW



SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE  
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE SHEET 1 EC NO: UCP2009-1813 DRWN:SDANNELLEY 2009/07/17 CHKD:BSMART 2009/07/24 APPR:SMILLER 2009/07/24	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	MM ONLY	1:1	METRIC	
	DESCRIPTION	ANGULAR ±1/2°	DRAWN BY DATE	TITLE		
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ELO 1998/05/21	SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)		
		SMR 1998/05/21	CHECKED BY DATE	MOLEX INCORPORATED		
		CAB 1998/05/21	APPROVED BY DATE	DOCUMENT NO. SDA-73656-*00*		
			MATERIAL NO.	SHEET NO. 4 OF 4		
			SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		